

Chip FabLab - A Project for Switzerland

Event "lunch@metagon" on 23 October 2025 at the Prime Tower in Zürich

Dr. Lars Sommerhäuser (Empa)

Without chips, our daily lives would come to a standstill















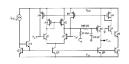


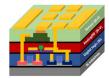


Chips and Microelectronics – Truly a Global Business

12 Steps - 10 Countries

From IP blocks and chip design ...





to fabrication of wafer and chips ...

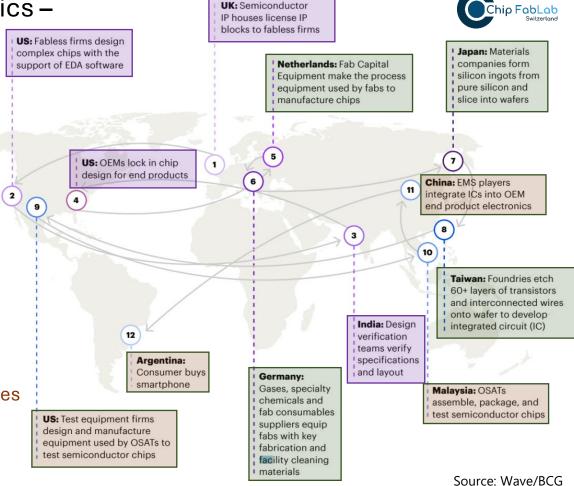




to the assembly of chip sets / phones

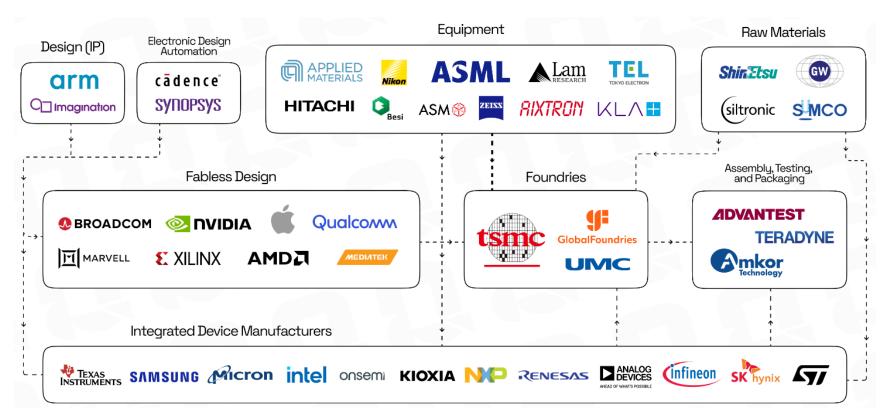






Key Players in the Global Semiconductor Value Chain





Source: Quartr Insights

Vision of the Chip FabLab Consortium



Make Switzerland one of the best places to develop and fabricate innovative semiconductor chips and modules for special applications in microelectronics, photonics and quantum technologies.

Chip FabLab – Project Overview



A Research, Development and Industrialization Platform for Switzerland



Key facts and figures

- National center to develop and fabricate semiconductor and photonics chips
- Non-profit limited company with partners from the public sector and industry
- Building with 4,000 m² of cleanroom and 7,000 m² of lab and office space at the Innovation Park Zürich (IPZ) in Dübendorf
- Operation of around 100 systems (CHF 129 million) for all steps from wafer to chip
- Services ranging from room rental and tool use to contract manufacturing (foundry services)

Consortium / Partner



SWISS**MEM**







Hitachi Energy



Applications Targeted by the Chip FabLab





Communications

Electrical and optical devices for signal processing and sensing, e.g. RF filters,
 THz modulators or detectors, or modules for RaDAR and LiDAR systems



Computing and Electronics

 Highly integrated chips for special applications, e.g. atomic clock chips for precision timing or ultra low power chips for watches and wearables



Power Electronics

 High power semiconductor devices in energy or mobility applications, e.g. SiC based inverters



Quantum Technologies

Building blocks for quantum computing, communication and sensing,
 e.g. superconducting, We are not aiming for the fabrication of
 mass manufactured logic or memory chips



Sensors

■ Electronic or photonic **for personal computers or smartphones** sor electromagnetic fields, e.g. contamination or humidity sensors

Technology Building Blocks, Components and Partners

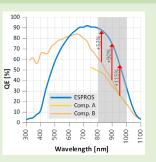


Sensors - Monolithic CCD/CMOS Chips for LIDAR Modules

Technology Building Blocks Fast backside illuminated imagers with 100% fill factor Monolithic CMOS/CCD mixed signal processing Research **Organizations ETH** zürich

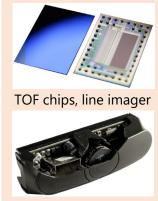
EPFL

Technical Advantages



- Very high sensitivity
 Quantum efficiency > 70%
 Conversion gain 80 µV/e-
- Ultra-high speed
 Pixel speed < 6 ns FWHM
 Time resolution = 10 ps
- High performance
 CTE = 0.9995 @ 250 MHz
 Up to 180 taps in pixel
 8 M electrons stored / pixel

Components



TOF/LiDAR modules

Swiss Manufacturer



Applications



Autonomous vehicles



Mobile robots / drones



Automation / logistics



Medical imaging

Military/Security Relevance

High precision LIDAR chips and modules:

- Autonomous navigation of UAV/UGV (drones and robots)
- Surveillance and intrusion detection
- Detection of mines or explosive devices
- Mapping and terrain analysis
- Identify, range, and track targets, e.g. for drones/missiles

Seven Reasons for Switzerland to Build the Chip FabLab







